

CLEAN VERSION OF NEW CLAIMS

Claim 21. A semiconductor stacking structure comprising:
a first semiconductor device; and
means coupled to a bottom surface of the first semiconductor
device for forming the semiconductor stacking structure wherein the
means is folded over on at least two sides to form flap portions
which are coupled to an upper surface of the first semiconductor
device and covers only a portion of the upper surface of the first
semiconductor device.

Claim 22. A semiconductor stacking structure in accordance
with Claim 21 further comprising means placed on the flap portions
of the flexible substrate for coupling the flap portions to the
first semiconductor device.

Claim 23. A semiconductor package in accordance with Claim 21
further comprising means placed on the upper surface of the first
semiconductor device for coupling the flap portions to the first
semiconductor device.

Claim 24. A semiconductor stacking structure in accordance with Claim 21 further comprising a second semiconductor device coupled to the flap portions of the means.

Claim 25. A semiconductor stacking structure in accordance with Claim 24 wherein the second semiconductor device is coupled to the flap portions of the means after the flap portions are folded over and coupled to the first semiconductor device.

Claim 26. A semiconductor stacking structure in accordance with Claim 24 wherein the second semiconductor device is coupled to the flap portions of the means before the flap portions are folded over and coupled to the first semiconductor device.

Claim 27. A semiconductor stacking structure package in accordance with Claim 21 wherein the semiconductor stacking structure is a LGA (Land Grid Array) device.

Claim 28. A semiconductor stacking structure in accordance with Claim 21 wherein the semiconductor stacking structure is a BGA (Ball Grid Array) device.